

### **Power MOSFET, 190 A**



PRODUCT SUMMARY					
$V_{\mathrm{DSS}}$	100 V				
I <sub>D</sub> DC	190 A				
R <sub>DS(on)</sub>	$0.0065~\Omega$				
Туре	Modules - MOSFET				
Package	SOT-227				

#### **FEATURES**

- Fully isolated package
- Very low on-resistance
- · Fully avalanche rated
- Dynamic dV/dt rating
- · Low drain to case capacitance
- · Low internal inductance
- · Optimized for SMPS applications
- · Easy to use and parallel
- · Industry standard outline
- · Designed and qualified for industrial level
- UL approved file E78996



• Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

#### **DESCRIPTION**

High current density power MOSFETs are paralleled into a compact, high power module providing the best combination of switching, ruggedized design, very low on-resistance and cost effectiveness.

The isolated SOT-227 package is preferred for all commercial-industrial applications at power dissipation levels to approximately higher than 500 W. The low thermal resistance and easy connection to the SOT-227 package contribute to its universal acceptance throughout the industry.

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS	
Continuous drain current at V <sub>GS</sub> 10 V	I <sub>D</sub>	T <sub>C</sub> = 40 °C	190		
		T <sub>C</sub> = 100 °C	130	Α	
Pulsed drain current	I <sub>DM</sub>		720		
Power dissipation	$P_{D}$	T <sub>C</sub> = 25 °C	568	W	
Linear derating factor			2.7	W/°C	
Gate to source voltage	V <sub>GS</sub>		± 20	V	
Single pulse avalanche energy	E <sub>AS</sub> (2)		700	mJ	
Avalanche current	I <sub>AR</sub> (1)		180	Α	
Repetitive avalanche energy	E <sub>AR</sub> (1)		48	mJ	
Peak diode recovery dV/dt	dV/dt (3)		5.7	V/ns	
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		- 55 to + 150	°C	
Insulation withstand voltage (AC-RMS)	V <sub>ISO</sub>		2.5	kV	
Mounting torque		M4 screw	1.3	Nm	

- (1) Repetitive rating; pulse width limited by maximum junction temperature.
- $\begin{array}{ll} \mbox{(2)} & \mbox{Starting T}_J = 25 \ ^{\circ}\mbox{C}, \ L = 43 \ \mu\mbox{H}, \ R_g = 25 \ \Omega, \ I_{AS} = 180 \ A. \\ \mbox{(3)} & \mbox{I}_{SD} \leq 180 \ A, \ d\mbox{I/dt} \leq 83 \ A\slash A\slash V_{DD} \leq V_{(BR)DSS}, \ T_J \leq 150 \ ^{\circ}\mbox{C}. \\ \end{array}$



THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		- 55	-	150	°C
Junction to case	$R_{thJC}$		-	-	0.22	°C/W
Case to heatsink	R <sub>thCS</sub>	Flat, greased surface	-	0.05	-	C/VV
Weight			-	30	-	g
Mounting torque			-	-	1.3	Nm
Case style				SOT	-227	

<b>ELECTRICAL CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Drain to source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	100	-	-	V
Breakdown voltage temperature coefficient	$\Delta V_{(BR)DSS}/\Delta T_J$	Reference to 25 °C, I <sub>D</sub> = 1 mA	-	0.093	-	V/°C
Static drain to source on-resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 180 A	-	0.0054	0.0065	Ω
Gate threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.0	3.3	4.35	V
Forward transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = 25 V, I <sub>D</sub> = 180 A	93	-	-	S
Duain to accuracy looks as a comment		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V	-	-	50	μА
Drain to source leakage current	I <sub>DSS</sub>	V <sub>DS</sub> = 80 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	500	
Gate to source forward leakage	I <sub>GSS</sub>	V <sub>GS</sub> = 20 V	-	-	200	- nA
		V <sub>GS</sub> = - 20 V	-	-	- 200	
Total gate charge	Qg	Q <sub>gs</sub> V <sub>DS</sub> = 80 V		250	-	
Gate to source charge	Q <sub>gs</sub>			40	-	nC
Gate to drain ("Miller") charge	$Q_{gd}$			110	-	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = 50 V	-	45	-	
Rise time	t <sub>r</sub>	I <sub>D</sub> = 180 A	-	351	-	
Turn-off delay time	t <sub>d(off)</sub>	$R_g = 2.0 \Omega$ (internal)	-	181	-	ns
Fall time	t <sub>f</sub>	$R_D = 0.27 \Omega$	-	335	-	1
Internal source inductance	L <sub>S</sub>	Between lead, and center of die contact	-	5.0	-	nH
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V	-	10 700	-	
Output capacitance	C <sub>oss</sub>	$V_{DS} = 25 \text{ V}$	-	2800	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1.0 MHz	-	1300	-	

SOURCE-DRAIN RATINGS AND CHARACTERISTICS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Continuous source current (body diode)	I <sub>S</sub>	MOSFET symbol	ı	-	190	Α
Pulsed source current (body diode)	I <sub>SM</sub>	showing the integral reverse p-n junction diode.	-	-	740	A
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 180 A, V <sub>GS</sub> = 0 V	=	1.0	1.3	V
Reverse recovery time	t <sub>rr</sub>	$T_J = 25  ^{\circ}\text{C},  I_F = 180  \text{A},  \text{dI/dt} = 100  \text{A/}\mu\text{s}$	-	300	-	ns
Reverse recovery charge	Q <sub>rr</sub>		=	2.6	-	μC
Forward turn-on time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by L <sub>S</sub> + L <sub>D</sub> )				

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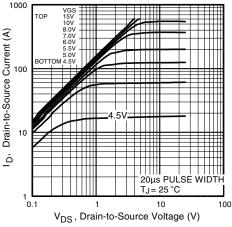
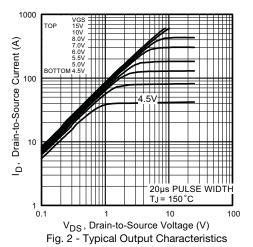


Fig. 1 - Typical Output Characteristics



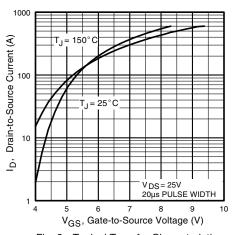


Fig. 3 - Typical Transfer Characteristics

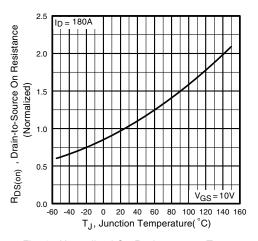


Fig. 4 - Normalized On-Resistance vs. Temperature

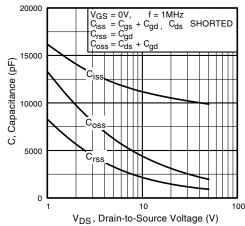


Fig. 5 - Typical Capacitance vs. Drain to Source Voltage

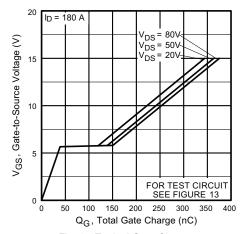


Fig. 6 - Typical Gate Charge vs. Gate to Source Voltage

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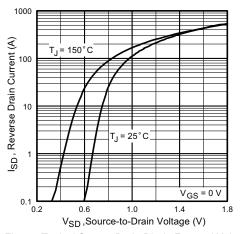


Fig. 7 - Typical Source Drain Diode Forward Voltage

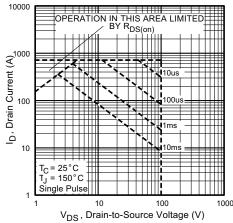


Fig. 8 - Maximum Safe Operating Area

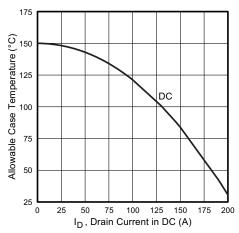


Fig. 9 - Maximum Drain Current vs. Case Temperature

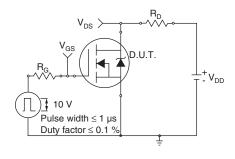


Fig. 10a - Switching Time Test Circuit

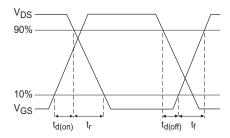


Fig. 10b - Switching Time Waveforms

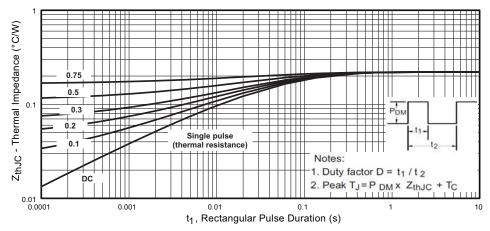


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction to Case

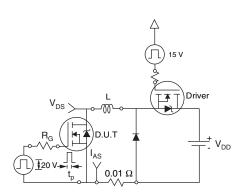


Fig. 12a - Unclamped Inductive Test Circuit

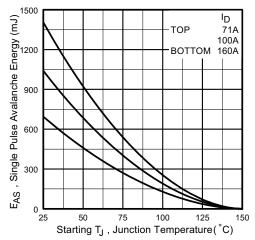


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

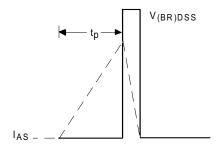


Fig. 12b - Unclamped Inductive Waveforms

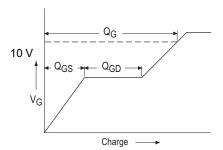


Fig. 13a - Basic Gate Charge Waveform

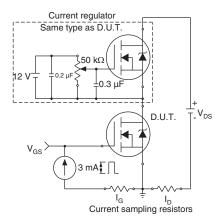


Fig. 13b - Gate Charge Test Circuit

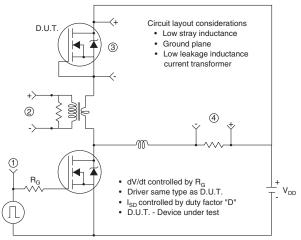


Fig. 13c - Peak Diode Recovery dV/dt Test Circuit

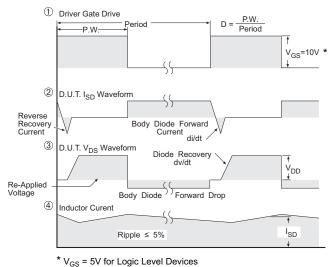
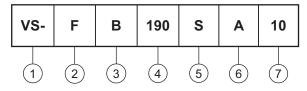


Fig. 14 - For N-Channel Power MOSFETs

#### **ORDERING INFORMATION TABLE**

**Device code** 



- 1 Vishay Semiconductors product
- 2 Power MOSFET
- 3 Generation 5 MOSFET
- 4 Current rating (190 = 190 A)
- 5 Single switch
- 6 Package indicator (SOT-227)
- 7 Voltage rating (10 = 100 V)

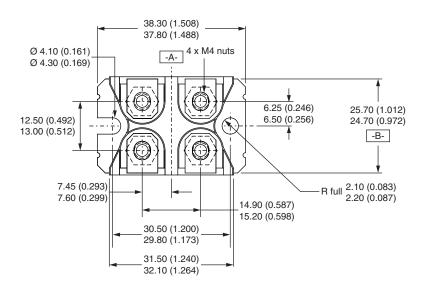
CIRCUIT CONFI	GURATION	
CIRCUIT	CIRCUIT CONFIGURATION CODE	CIRCUIT DRAWING
Single switch	S	G (2)  Lead Assignment  (S)  (D)  4  1  (S)  (S)  (G)  (S)  (S)  (S)  (S)  (S)

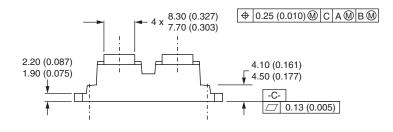
LINKS TO RELATED DOCUMENTS				
Dimensions <u>www.vishay.com/doc?95423</u>				
Packaging information	www.vishay.com/doc?95425			

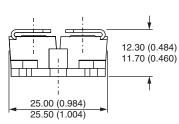


#### **SOT-227 Generation II**

#### **DIMENSIONS** in millimeters (inches)







#### Note

Controlling dimension: millimeter



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